

UH114

Manual wafer / frame film mounter



HIGHLIGHTS

- ▶ Roller pressure adjust
- ▶ Fast lamination
- ▶ UV tape film take up
- ▶ ESD option

SPECIFICATIONS

- ▶ Manual roller
- ▶ Frame style choice
- ▶ Thermal chuck
- ▶ Circular and linear cutter

microworld®

Grenoble -FRANCE

Tel. +33 (0)4 76 56 16 17

Contact@microworld.eu

www.microworld.eu



The Models UH114 set the benchmark for control and versatility. For dicing/sawing applications, uniform adhesive plastic film lamination is paramount. The mounters feature an easily adjustable spring-loaded roller assembly, along with film tensioner bars along both the x- and y-axes to assure bubble-free lamination of the film to the wafer and film frame. In addition, both models feature a retractable film cutting system with adjustable cutting pressure to accommodate various tape base materials and thicknesses. Roller pressure is adjusted from the topside of the units for different process requirements and to accommodate various wafer thicknesses. A digital temperature controller assures consistent workstage temperatures for repeatable mounting. Adjustable alignment pins and vacuum cups accommodate almost any type of film frame, including plastic. The workstage height is also adjustable relative to the frame height for different wafer thicknesses.

Features

- Up to 12" wafer capability standard
- Manual film lamination (single-pass with UH114-12 only)
- Adjustable roller pressure
- Temperature controlled platen
- Built-in circular cutter (wheel type) for cutting film on film frame
- Spring-loaded tensioner bar
- Vacuum securing wafer
- Build-in end cutter for film separation
- Accommodates film/protective layer wound on the outside or inside

Models

UH114	For wafer up to 6" (150 mm)
UH114-8	For wafer up to 8" (200 mm)
UH114-12	For wafer up to 12" (300 mm)

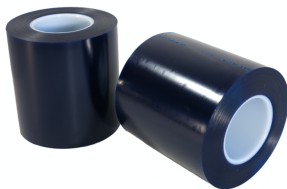
Configurations & options

- Protective film take-up roller assembly
Wrap the protective film of UV tape during take up
- Static eliminator by ionizing bar
Prevent ESD discharge during film take up
- Standard Wafer Stage/Chuck
Choice of standard chuck (from 2" to 12" following version)

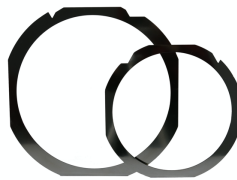
- Thin Wafer Stage/Chuck
- Adapter for wafer frame
Adapat the style and size of user frame in the machine

Specifications

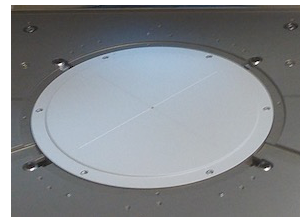
Wafer holding	Vacuum
Chuck temprature	Up to 60°C
UV tape capable	UV protection cover
Tape cutting	Rear linear knife & frame circular wheel
Roller pressure adjust	Mechanical (2 tension screws)
Power supply	240 VAC / 50 Hz / 0.5A (single phase)
Vacuum	25 in Hg – 1/4" OD push in



Standard and UV tapes



Film frames



Chuck choice